MEMS LID-ATTACH Solder Paste

- Dispenses consistently
- Reduces blow holes and solder creep
- Suitable for all high-melting alloys (220-255°C)
- No-intentionally-added halogens [halogen-free flux]

Improve yields with:

Halogen-Free, No-Clean Pastes

Indium8.9HF Solder Paste

- Standard colorless residue
- Airless syringe packaging
- Complete wetting reduces blow holes
- Long dispense life

NC-SMQ®77 Solder Paste

- Ultra-low residue
- Does not contaminate MEMS surfaces with flux spatter
- Airless syringe packaging
- Proven in HVM

Contact our expert today: amackie@indium.com Learn more: www.indium.com/MEMS



MEMS LID-ATTACH Solder Paste

Next generation materials for microelectronics:

New technologies and the continuing demand for miniaturization are driving the need for increasingly smaller components in electronics assembly. Indium Corporation provides solutions for the challenges found in microelectronics industry with the next generation materials – from semiconductor and advanced assembly materials to engineered solders.



Flip-Chip Fluxes

- Semiconductor-grade
- Water-soluble, ultra-low residue (no-clean)
- Halogen-free
- Proven in HVM
- Dip and spray available



Ball-Attach Fluxes

- One-step OSP materials available
- Suitable for pin-transfer applications
- Excellent solderability on a wide range of surfaces
- Water-soluble and no-clean

Standard Alloys

Indalloy® Number	Liquidus °C	Solidus °C	Elemental Composition (% by Mass)
121	221 Eutectic		96.5Sn/3.5Ag
267	224	221	97.0Sn/3.0Ag
123	226	221	97.5Sn/2.5Ag
243	227 Eutectic		99.0Sn/1.0Cu
244	227 Eutectic		99.3Sn/0.7Cu
262 (Sn995)	227 Eutectic		99.5Sn/0.5Cu
129	234	232	99.0Sn/1.0Sb
131	237	235	97.0Sn/3.0Sb
132	240	221	95.0Sn/5.0Ag
133	240	237	95.0Sn/5.0Sb
264	248	241	91.5Sn/8.5Sb
259	257	243	90.0Sn/10.0Sb
143	260	252	90.0Pb/10.0Sb
SMT-BiAgX®	262	285	Proprietary
10	267	235	75.0Pb/25.0In
150	275	260	81.0Pb/19.0In
182	280 Eutectic		80.0Au/20.0Sn



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